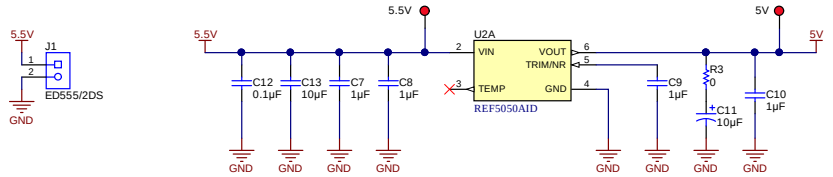
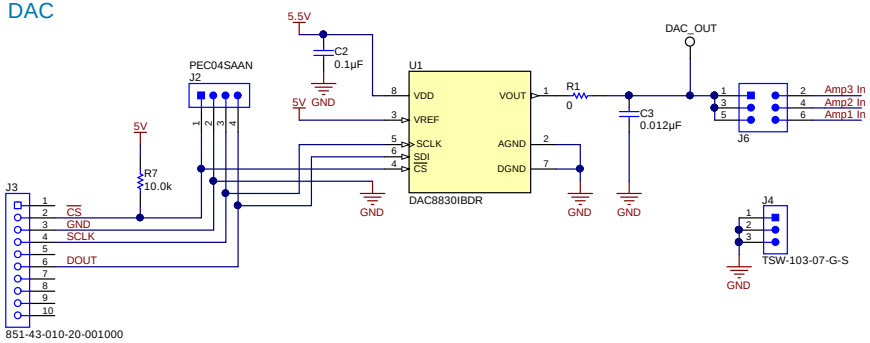
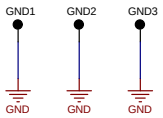
Power



DAC

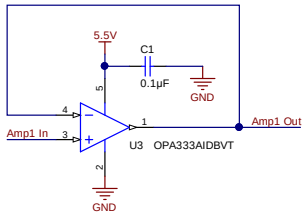


Ground Test Points

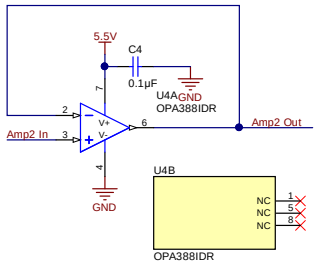


Buffer

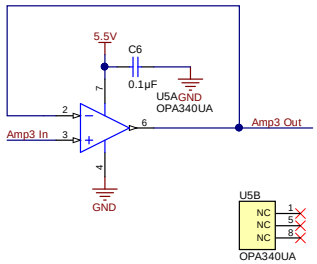
Amplifer 1



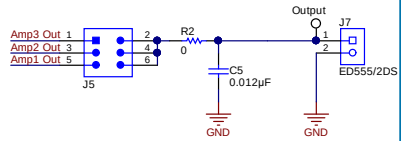
Amplifer 2



Amplifer 3



Output Load



Orderable: EVM_orderable		Designed for:Public Release	Mod. Date: 2/3/2017
TID #: TIDA01402		Project Title:Minimizing DAC INL with zero-crossover op amp	
Number:TIDA01402	Rev: E1	Sheet Title:	
EVM Rev: Version control disabled		Assembly Variant:[No Variations]	Sheet:2 of 3
Drawn By:		File: TIDA01402-Schematic.SchDoc	Size: B
Engineer: Errol Leon		Contact: http://www.ti.com/support	

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